

CMOS SyncFIFO[™] 64 x 8, 256 x 8, 512 x 8, 1,024 x 8, 2,048 x 8 and 4,096 x 8

IDT72420 IDT72200 IDT72210 IDT72220 IDT72230 IDT72240

LEAD FINISH (SnPb) ARE IN EOL PROCESS - LAST TIME BUY EXPIRES JUNE 15, 2018

FEATURES:

- 64 x 8-bit organization (IDT72420)
- 256 x 8-bit organization (IDT72200)
- 512 x 8-bit organization (IDT72210)
- 1,024 x 8-bit organization (IDT72220)
- 2,048 x 8-bit organization (IDT72230)
- 4,096 x 8-bit organization (IDT72240)
- 10 ns read/write cycle time (IDT72420/72200/72210/72220/72230/ 72240)
- Read and Write Clocks can be asynchronous or coincidental
- Dual-Ported zero fall-through time architecture
- Empty and Full flags signal FIFO status
- Almost-Empty and Almost-Full flags set to Empty+7 and Full-7, respectively
- · Output enable puts output data bus in high-impedance state
- Produced with advanced submicron CMOS technology
- Available in 28-pin 300 mil plastic DIP
- For surface mount product please see the IDT72421/72201/72211/ 72221/72231/72241 data sheet
- Green parts available, see ordering information

DESCRIPTION:

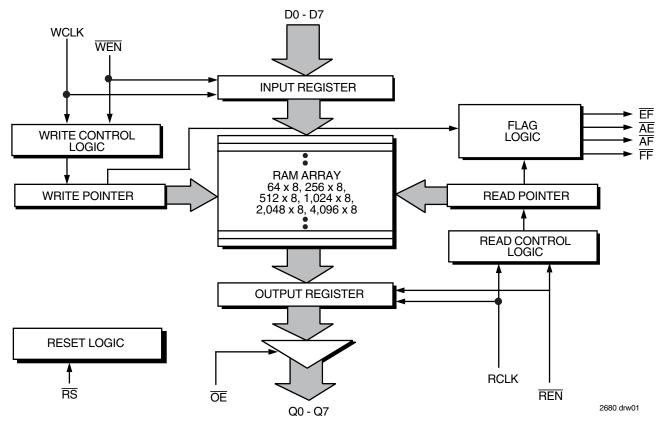
The IDT72420/72200/72210/72220/72230/72240 SyncFIFOTM are very high-speed, low-power First-In, First-Out (FIFO) memories with clocked read and write controls. These devices have a 64, 256, 512, 1,024, 2,048, and 4,096 x 8-bit memory array, respectively. These FIFOs are applicable for a wide variety of data buffering needs, such as graphics, Local Area Networks (LANs), and interprocessor communication.

These FIFOs have 8-bit input and output ports. The input port is controlled by a free-running clock (WCLK), and a Write Enable pin (WEN). Data is written into the Synchronous FIFO on every clock when WEN is asserted. The output port is controlled by another clock pin (RCLK) and a Read Enable pin (REN). The Read Clock can be tied to the Write Clock for single clock operation or the two clocks can run asynchronous of one another for dual clock operation. An Output Enable pin (\overline{OE}) is provided on the read port for three-state control of the output.

These Synchronous FIFOs have two endpoint flags, Empty (\overline{EF}) and Full (\overline{FF}). Two partial flags, Almost-Empty (\overline{AE}) and Almost-Full (\overline{AF}), are provided for improved system control. The partial (\overline{AE}) flags are set to Empty+7 and Full-7 for \overline{AE} and \overline{AF} respectively.

These FIFOs are fabricated using high-speed submicron CMOS technology.

FUNCTIONAL BLOCK DIAGRAM

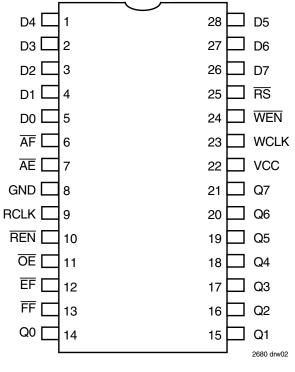


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COMMERCIAL TEMPERATURE RANGE

FEBRUARY 2018

PIN CONFIGURATION



PLASTIC THIN DIP (P28-2, order code: TP) TOP VIEW

PIN DESCRIPTIONS

Symbol	Name	I/O	Description
D0 - D7	Data Inputs	Ι	Data inputs for a 8-bit bus.
RS	Reset	Ι	When \overline{RS} is set LOW, internal read and write pointers are set to the first location of the RAM array, \overline{FF} and \overline{AF} go HIGH, and \overline{AE} and \overline{EF} go LOW. A reset is required before an initial WRITE after power-up.
WCLK	Write Clock	Ι	Data is written into the FIFO on a LOW-to-HIGH transition of WCLK when WEN is asserted.
WEN	Write Enable	I	When WEN is LOW, data is written into the FIFO on every LOW-to-HIGH transition of WCLK. Data will not be written into the FIFO if the FF is LOW.
Q0 - Q7	Data Outputs	0	Data outputs for a 8-bit bus.
RCLK	Read Clock	Ι	Data is read from the FIFO on a LOW-to-HIGH transition of RCLK when $\overline{\text{REN}}$ is asserted.
REN	Read Enable	Ι	When $\overline{\text{REN}}$ is LOW, data is read from the FIFO on every LOW-to-HIGH transition of RCLK. Data will not be read from the FIFO if the $\overline{\text{EF}}$ is LOW.
ŌĒ	Output Enable	Ι	When \overline{OE} is LOW, the data output bus is active. If \overline{OE} is HIGH, the output data bus will be in a high-impedance state.
ĒF	Empty Flag	0	When \overline{EF} is LOW, the FIFO is empty and further data reads from the output are inhibited. When \overline{EF} is HIGH, the FIFO is not empty. \overline{EF} is synchronized to RCLK.
ĀĒ	Almost-Empty Flag	0	When \overline{AE} is LOW, the FIFO is almost empty based on the offset Empty+7. \overline{AE} is synchronized to RCLK.
ĀF	Almost-Full Flag	0	When \overline{AF} is LOW, the FIFO is almost full based on the offset Full-7. \overline{AF} is synchronized to WCLK.
FF	Full Flag	0	When \overline{FF} is LOW, the FIFO is full and further data writes into the input are inhibited. When \overline{FF} is HIGH, the FIFO is not full. \overline{FF} is synchronized to WCLK.
Vcc	Power		One +5 volt power supply pin.
GND	Ground		One 0 volt ground pin.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Rating	Com'l & Ind'l	Unit
VTERM	Terminal Voltage with	–0.5 to +7.0	V
	Respect to GND		
Tstg	Storage Temperature	–55 to +125	С
Іоит	DC Output Current	-50 to +50	mA

NOTE:

 Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min.	Тур.	Max.	Unit
Vcc	Supply Voltage	4.5	5.0	5.5	V
	Commercial				
GND	Supply Voltage	0	0	0	V
Vih	Input High Voltage	2.0	—	—	V
	Commercial				
Vil	Input Low Voltage	—	—	0.8	V
	Commercial				
ΤΑ	Operating Temperature	0	_	70	°C
	Commercial				

DC ELECTRICAL CHARACTERISTICS

(Commercial: $VCC = 5V \pm 10\%$, $TA = 0^{\circ}C$ to $+70^{\circ}C$)

		IDT724 IDT722 IDT722 IDT722 IDT722 IDT722 Commen tCLK = 10, 1	00 10 20 30 40 rcial		
Symbol	Parameter	Min.	Тур.	Max.	Unit
LI ⁽¹⁾	Input Leakage Current (any input)	-1	_	1	μA
LO ⁽²⁾	Output Leakage Current	-10	_	10	μA
Vон	Output Logic "1" Voltage, IOH = -2 mA	2.4	_		V
Vol	Output Logic "0" Voltage, IOL = 8 mA	_	_	0.4	V
ICC1 ^(3,4,5)	Active Power Supply Current		_	40	mA
ICC2 ^(3,6)	Standby Current			5	mA

NOTES:

1. Measurements with $0.4 \leq V_{IN} \leq V_{CC}$.

2. $\overline{OE} \ge V_{IH}, 0.4 \le V_{OUT} \le V_{CC}.$

3. Tested with outputs open (IOUT = 0).

4. RCLK and WCLK toggle at 20 MHz and data inputs switch at 10 MHz.

 Typical Icc1 = 1.7 + 0.7*fs + 0.02*CL*fs (in mA). These equations are valid under the following conditions: Vcc = 5V, TA = 25°C, fs = WCLK frequency = RCLK frequency (in MHz, using TTL levels), data switching at fs/2, CL = capacitive load (in pF).

6. All Inputs = Vcc - 0.2V or GND + 0.2V, except RCLK and WCLK, which toggle at 20 MHz.

AC ELECTRICAL CHARACTERISTICS

(Commercial: $VCC = 5V \pm 10\%$, TA = 0°C to + 70°C)

			Commercial					
			IDT72420L10 IDT72200L10 IDT72210L10 IDT72220L10 IDT72230L10 IDT72240L10		IDT72420L15 IDT72200L15 IDT72210L15 IDT72220L15 IDT72230L15 IDT72240L15		IDT72420L25 IDT72200L25 IDT72210L25 IDT72220L25 IDT72230L25 IDT72230L25 IDT72240L25	
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Unit
fs	Clock Cycle Frequency	-	100	—	66.7	_	40	MHz
tA	Data Access Time	2	6.5	2	10	2	15	ns
tclk	Clock Cycle Time	10	_	15	_	25	_	ns
t CLKH	Clock High Time	4.5	_	6	—	10	—	ns
t CLKL	Clock Low Time	4.5	—	6	—	10	—	ns
tDS	Data Setup Time	3	—	4	—	6	—	ns
ťDH	Data Hold Time	0.5	—	1	—	1	_	ns
tens	Enable Setup Time	3	—	4	—	6	—	ns
tenh	Enable Hold Time	0.5	—	1	—	1	—	ns
tRS	Reset Pulse Width ⁽¹⁾	10	_	15	_	15	_	ns
tRSS	Reset Setup Time	8	—	10	—	15	—	ns
tRSR	Reset Recovery Time	8	—	10	—	15	_	ns
tRSF	Reset to Flag and Output Time	-	10	_	15	-	25	ns
tolz	Output Enable to Output in Low-Z ⁽²⁾	0	—	0	—	0	-	ns
toe	Output Enable to Output Valid	2	6	3	8	3	13	ns
tонz	Output Enable to Output in High-Z ⁽²⁾	2	6	3	8	3	13	ns
tWFF	Write Clock to Full Flag	-	6.5	_	10	-	15	ns
t REF	Read Clock to Empty Flag	_	6.5	_	10	—	15	ns
taf	Write Clock to Almost-Full Flag	-	6.5	_	10	_	15	ns
tAE	Read Clock to Almost-Empty Flag	_	6.5	_	10	_	15	ns
tskew1	Skew time between Read Clock & Write Clock for Empty Flag & Full Flag	4	_	6	—	10	—	ns
tskew2	Skew time between Read Clock & Write Clock for Almost-Empty Flag & Almost-Full Flag	10	_	15	-	18	_	ns

NOTES:

1. Pulse widths less than minimum values are not allowed.

2. Values guaranteed by design, not currently tested.

CAPACITANCE (TA = +25°C, f = 1.0 MHz)

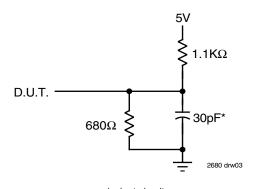
Symbol	Parameter	Conditions	Max.	Unit
CIN ⁽²⁾	Input Capacitance	VIN = 0V	10	pF
COUT (1, 2)	Output Capacitance	Vout = 0V	10	pF

NOTES:

1. With output deselected. ($\overline{OE} \ge VIH$) 2. Characterized values, not currently tested.

AC TEST CONDITIONS

ſ	Input Pulse Levels	GND to 3.0V
l	Input Rise/Fall Times	3ns
l	Input Timing Reference Levels	1.5V
l	Output Reference Levels	1.5V
l	Output Load	See Figure 1



or equivalent circuit Figure 1. Output Load *Includes jig and scope capacitances.

SIGNAL DESCRIPTIONS

INPUTS:

Data In (Do–D7) — Data inputs for 8-bit wide data.

CONTROLS:

RESET (**RS**) — Reset is accomplished whenever the Reset (**RS**) input is taken to a LOW state. During reset, both internal read and write pointers are set to the first location. A reset is required after power up before a write operation can take place. The Full Flag (**FF**) and Almost-Full Flag (**AF**) will be reset to HIGH after tRSF. The Empty Flag (**EF**) and Almost-Empty Flag (**AE**) will be reset to LOW after tRSF. During reset, the output register is initialized to all zeros.

WRITE CLOCK (WCLK) — A write cycle is initiated on the LOW-to-HIGH transition of the Write Clock (WCLK). Data setup and hold times must be met in respect to the LOW-to-HIGH transition of the Write Clock. The Full Flag (\overline{FF}) and Almost-Full Flag (\overline{AF}) are synchronized with respect to the LOW-to-HIGH transition of the Write Clock.

The Write and Read Clocks can be asynchronous or coincident.

WRITE ENABLE (WEN) — When Write Enable (WEN) is LOW, data can be loaded into the input register and RAM array on the LOW-to-HIGH transition of every Write Clock (WCLK). Data is stored in the RAM array sequentially and independently of any on-going read operation.

When Write Enable (WEN) is HIGH, the input register holds the previous data and no new data is allowed to be loaded into the register.

To prevent data overflow, the Full Flag (FF) will go LOW, inhibiting further write operations. Upon the completion of a valid read cycle, the Full Flag (FF) will go HIGH after twFF, allowing a valid write to begin. Write Enable (WEN) is ignored when the FIFO is full.

READ CLOCK (RCLK) — Data can be read on the outputs on the LOW-to-HIGH transition of the Read Clock (RCLK). The Empty Flag ($\overline{\text{EF}}$) and Almost-Empty flag ($\overline{\text{AE}}$) are synchronized with respect to the LOW-to-HIGH transition of the Read Clock.

The Write and Read Clocks can be asynchronous or coincident.

READ ENABLE (**REN**) — When Read Enable (**REN**) is LOW, data is read from the RAM array to the output register on the LOW-to-HIGH transition of the Read Clock (RCLK).

When Read Enable (REN) is HIGH, the output register holds the previous data and no new data is allowed to be loaded into the register.

When all the data has been read from the FIFO, the Empty Flag (\overline{EF}) will go LOW, inhibiting further read operations. Once a valid write operation has been accomplished, the Empty Flag (\overline{EF}) will go HIGH after tREF and a valid read can begin. Read Enable (\overline{REN}) is ignored when the FIFO is empty.

OUTPUT ENABLE (\overline{OE}) — When Output Enable (\overline{OE}) is enabled (LOW), the parallel output buffers receive data from the output register. When Output Enable (\overline{OE}) is disabled (HIGH), the Q output data bus is in a high-impedance state.

OUTPUTS:

FULL FLAG (FF) — The Full Flag (FF) will go LOW, inhibiting further write operation, when the device is full. If no reads are performed after Reset (RS), the Full Flag (FF) will go LOW after 64 writes for the IDT72420, 256 writes for the IDT72200, 512 writes for the IDT72210, 1,024 writes for the IDT72220, 2,048 writes for the IDT72230, and 4,096 writes for the IDT72240.

The Full Flag (FF) is synchronized with respect to the LOW-to-HIGH transition of the Write Clock (WCLK).

EMPTY FLAG (EF) — The Empty Flag ($\overline{\text{EF}}$) will go LOW, inhibiting further read operations, when the read pointer is equal to the write pointer, indicating the device is empty.

The Empty Flag (EF) is synchronized with respect to the LOW-to-HIGH transition of the Read Clock (RCLK).

ALMOST-FULL FLAG (\overline{AF}) — The Almost-Full Flag (\overline{AF}) will go LOW when the FIFO reaches the almost-full condition. If no reads are performed after Reset (\overline{RS}), the Almost-Full Flag (\overline{AF}) will go LOW after 57 writes for the IDT72420, 249 writes for the IDT72200, 505 writes for the IDT72210, 1,017 writes for the IDT72220, 2,041 writes for the IDT72230 and 4,089 writes for the IDT72240.

The Almost-Full Flag (\overline{AF}) is synchronized with respect to the LOW-to-HIGH transition of the Write Clock (WCLK).

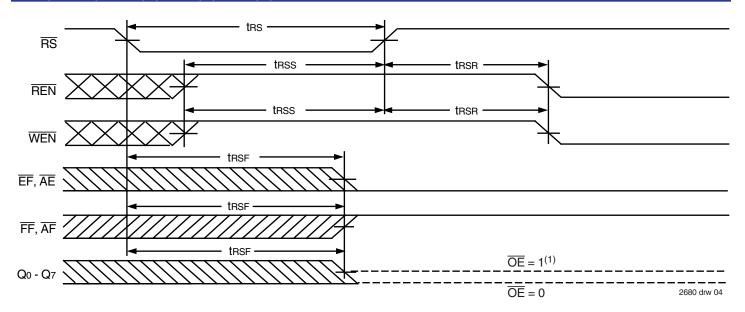
ALMOST-EMPTY FLAG (\overline{AE}) — The Almost-Empty Flag (\overline{AE}) will go LOW when the FIFO reaches the almost-empty condition. If no reads are performed after Reset (\overline{RS}), the Almost-Empty Flag (\overline{AE}) will go HIGH after 8 writes for the IDT72420, IDT72200, IDT72210, IDT72220, IDT72230 and IDT72240.

The Almost-Empty Flag (AE) is synchronized with respect to the LOWto-HIGH transition of the Read Clock (RCLK).

DATA OUTPUTS (Q0–Q7) — Data outputs for 8-bit wide data.

	Number of Words in FIFO								
IDT72420	IDT72200	IDT72210	IDT72220	IDT72230	IDT72240	FF	ĀĒ	ĀĒ	ĒF
0	0	0	0	0	0	Н	Н	L	L
1 to 7	1 to 7	1 to 7	1 to 7	1 to 7	1 to 7	Н	Н	L	Н
8 to 56	8 to 248	8 to 504	8 to 1,016	8 to 2,040	8 to 4,088	Н	Н	Н	Н
57 to 63	249 to 255	505 to 511	1,017 to 1,023	2,041 to 2,047	4,089 to 4,095	Н	L	Н	Н
64	256	512	1,024	2,048	4,096	L	L	Н	Н

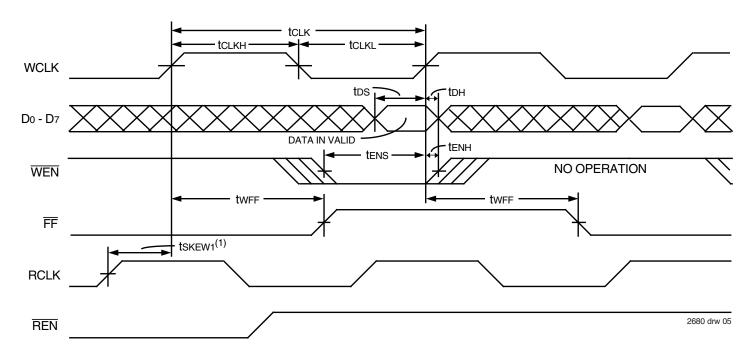
TABLE 1 — STATUS FLAGS



NOTES:

- 1. After reset, the outputs will be LOW if $\overline{OE} = 0$ and three-state if $\overline{OE} = 1$.
- 2. The Clocks (RCLK, WCLK) can be free-running during reset.

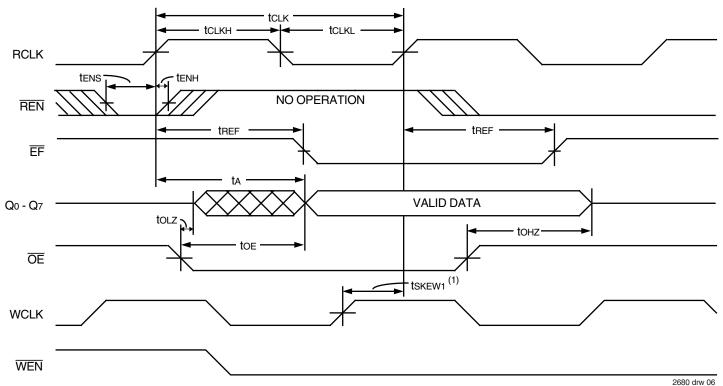




NOTE:

tskEw1 is the minimum time between a rising RCLK edge and a rising WCLK edge for FF to change during the current clock cycle. If the time between the rising edge of RCLK and the rising edge of WCLK is less than tskEw1, then FF may not change state until the next WCLK edge.

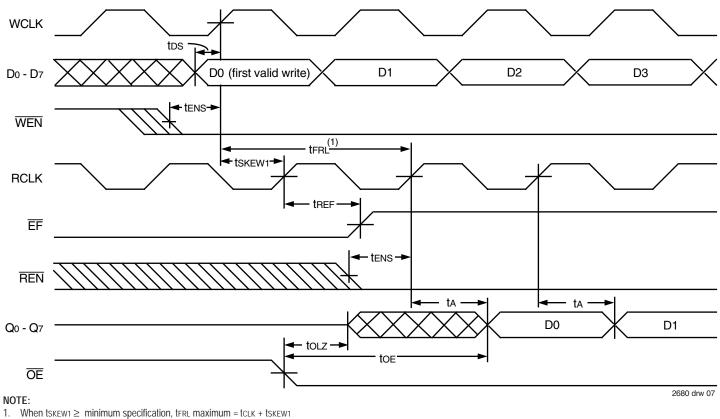
Figure 3. Write Cycle Timing



NOTE:

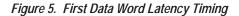
tskEW1 is the minimum time between a rising WCLK edge and a rising RCLK edge for EF to change during the current clock cycle. If the time between the rising edge of WCLK and the rising edge of RCLK is less than tskEW1, then EF may not change state until the next RCLK edge.

Figure 4. Read Cycle Timing



tskew1 < minimum specification, tFRL maximum = 2tcLK + tskew1 or tcLK + tskew1

The Latency Timing apply only at the Empty Boundary ($\overline{EF} = LOW$).



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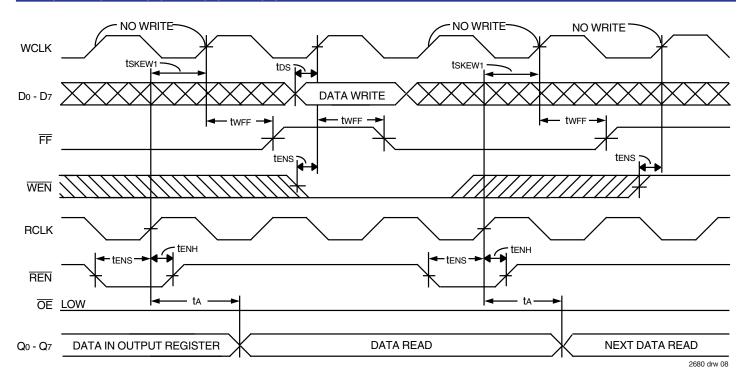
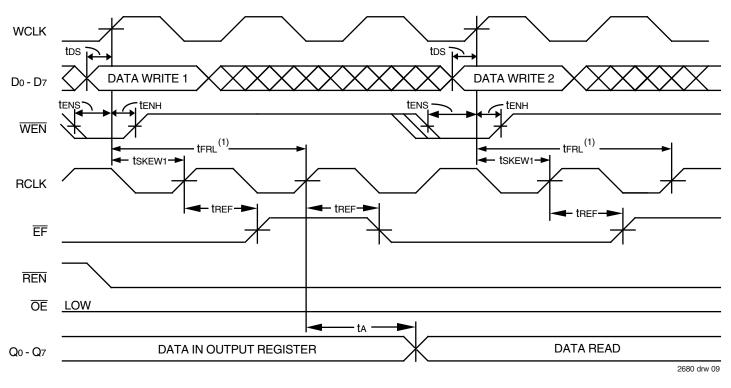


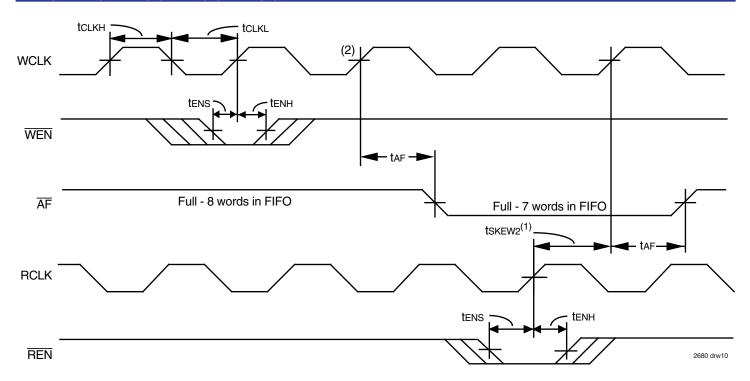
Figure 6. Full Flag Timing



NOTE:

 When tskew1 ≥ minimum specification, tFRL maximum = tcLK + tskew1 tskew1 < minimum specification, tFRL maximum = 2tcLK + tskew1 or tcLK + tskew1 The Latency Timing apply only at the Empty Boundary (EF = LOW).

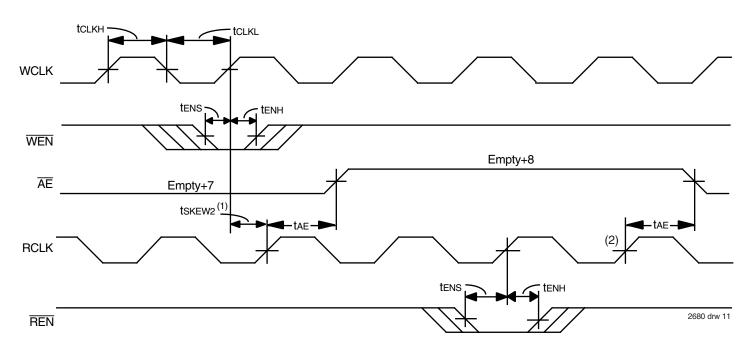
Figure 7. Empty Flag Timing



NOTES:

- tskew2 is the minimum time between a rising RCLK edge and a rising WCLK edge for AF to change during the current clock cycle. If the time between the rising edge of RCLK and the rising edge of WCLK is less than tskew2, then AF may not change state until the next WCLK edge.
- 2. If a write is performed on this rising edge of the Write Clock, there will be Full -7 words in the FIFO when AF goes LOW.

Figure 8. Almost Full Flag Timing



NOTES:

- 1. tskew2 is the minimum time between a rising WCLK edge and a rising RCLK edge for \overline{AE} to change during the current clock cycle. If the time between the rising edge of WCLK and the rising edge of RCLK is less than tskew2, then \overline{AE} may not change state until the next RCLK edge.
- 2. If a read is performed on this rising edge of the Read Clock, there will be Empty +7 words in the FIFO when AE goes LOW.

Figure 9. Almost Empty Flag Timing

OPERATING CONFIGURATIONS

SINGLE DEVICE CONFIGURATION - A single IDT72420/72200/72210/ 72220/72230/72240 may be used when the application requirements are for 64/256/512/1,024/2,048/4,096 words or less. See Figure 10.

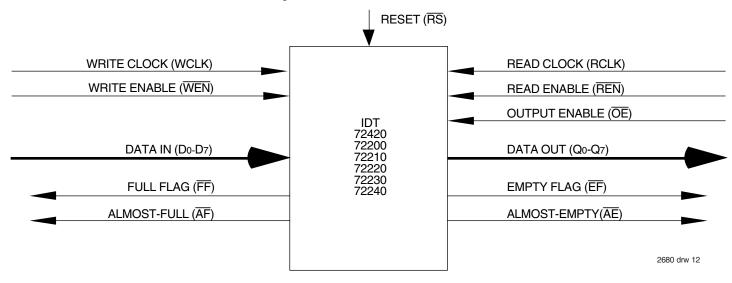


Figure 10. Block Diagram of Single 64 x 8, 256 x 8, 512 x 8, 1,024 x 8, 2,048 x 8, 4,096 x 8 Synchronous FIFO

WIDTH EXPANSION CONFIGURATION - Word width may be increased simply by connecting the corresponding input control signals of multiple devices. A composite flag should be created for each of the endpoint status flags ($\overline{\text{EF}}$ and $\overline{\text{FF}}$) The partial status flags ($\overline{\text{AE}}$ and $\overline{\text{AF}}$) can be detected from any one device. Figure 11 demonstrates a 16-bit word width by using two IDT72420/72200/72210/72220/72230/72240s. Any word width can be attained by adding additional IDT72420/72200/72210/72220/72230/72240s.

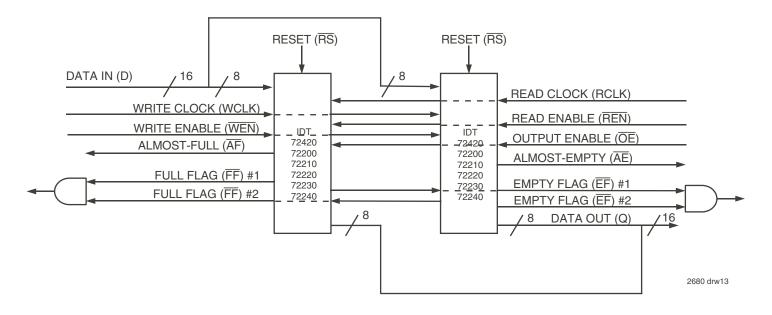


Figure 11. Block Diagram of 64 x 16, 256 x 16, 512 x 16, 1,024 x 16, 2,048 x 16, 4,096 x 16 Synchronous FIFO Used in a Width Expansion Configuration

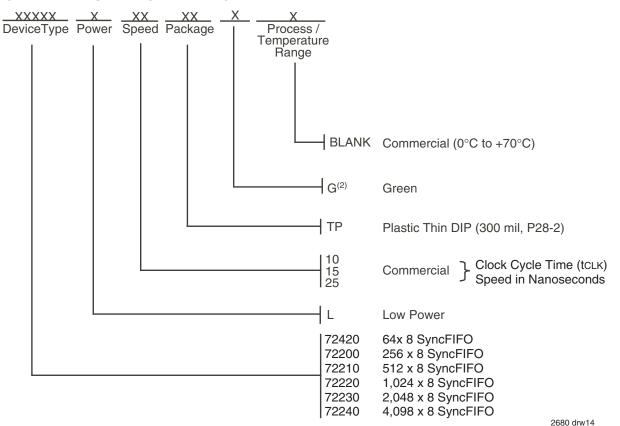
DEPTH EXPANSION

The IDT72420/72200/72210/72220/72230/72240 can be adapted to applications when the requirements are for greater than 64/256/512/1,024/2,048/4,096 words. Depth expansion is possible by using expansion logic to direct the flow of data. A typical application would have the expansion logic

ORDERING INFORMATION

alternate data accesses from one device to the next in a sequential manner.

Please see the Application Note "DEPTH EXPANSION IDT'S SYNCHRONOUS FIFOS USING RING COUNTER APPROACH" for details of this configuration.



NOTES:

 Green parts are available. For specific speeds and packages contact your sales office. LEAD FINISH (SnPb) parts are in EOL process. Product Discontinuation Notice - PDN# SP-17-02

DATASHEET DOCUMENT HISTORY

10/03/2000	pgs. 1, 3, 4 and 11.
05/01/2001	pgs. 1, 2, 3, 4 and 11.
02/10/2006	pgs. 1 and 11.
01/08/2009	pg. 11.
07/25/2013	pgs. 1, 3, 9 and 10.
02/12/2018	Product Discontinuation Notice - PDN# SP-17-02
	Last time buy expires June 15, 2018.

^{1.} Industrial temperature range is available by special order.

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